

AMENDMENTS TO THE CLAIMS

Please amend the claims as follows:

Claims 1-3 (Cancelled)

Claim 4 (Currently Amended): An electronic device comprising:

a heat spreader joined to a die or an electronic part, said heat spreader comprising a material having a coefficient of thermal expansion approximate to that of said electronic part, wherein said electric part is cooled by transferring heat generated in said electric part to said heat spreader.

Claim 5 (Currently Amended): The electronic device according to Claim 4,

wherein said die or electronic part is comprised of silicon, and

wherein said heat spreader is comprised of nickel steel or aluminum nitride.

Claim 6 (Original): The electronic device according to Claim 4,

wherein said heat spreader is comprised of invar.

Claim 7 (Currently Amended): The electronic device according to Claim 4,

wherein said electronic device comprises graphite located between said die or electronic part and said heat spreader.

Claim 8 (Currently Amended): The electronic device according to Claim 7,

wherein said die or electronic part, said heat spreader and said graphite are joined with an adhesive or a solder.

Claim 9 (Original): The electronic device according to Claim 7,
wherein said heat spreader and said graphite are joined by a diffused junction method.

Claim 10 (Original): A heat radiating structure for cooling an electronic device
comprising:

a heat spreader with a chamber formed in said heat spreader comprised of a sealed
structure encapsulating a condensable fluid therein which can repeatedly evaporate and
condense to transport heat.

Claim 11 (Original): A heat radiating structure for cooling an electronic device
comprising:

a heat spreader, wherein said heat spreader comprises aluminum and further
comprises a lubricating member buried in one face of said heat spreader.

Claim 12 (Original): The heat radiating structure according to Claim 11,
wherein said face is anodized to form fine cracks therein, which cracks are filled with
molybdenum sulfide comprised as said lubricating member.

Claim 13 (Cancelled)

Claim 14 (Currently Amended): An electronic device comprising a die or an
electronic part, a heat radiating structure and a heat spreader, wherein

said spreader comprises a chamber formed in said heat spreader comprised of a sealed structure encapsulating a condensable fluid therein which can repeatedly evaporate and condensate to transport heat.

Claim 15 (Currently Amended): An electronic device comprising a die or an electronic part, a heat radiating structure and a heat spreader,

wherein said heat spreader comprises of aluminum and further comprises a lubricating member buried in the face of said heat spreader on the side of said die or electronic part.

Claim 16 (Original): The electronic device according to Claim 15,
wherein said face is anodized to form fine cracks therein, which cracks are filled with molybdenum sulfide comprised as said lubricating member.

Claim 17 (Original): The electronic device according to Claim 6, wherein said invar comprises 0.4% Mn, 0.2% C, 36% Ni, and the remainder Fe.

Claim 18-21 (Cancelled)

Claim 22 (New): The electronic device of Claim 4, which comprises a heat spreader joined to an electronic part.

Claim 23 (New): The electronic device of Claim 4, which comprises a heat spreader joined to a die.

Claim 24 (New): The electronic device of Claim 4, which is an MPU.

Claim 25 (New): The electronic device of Claim 4, which is an image processor.